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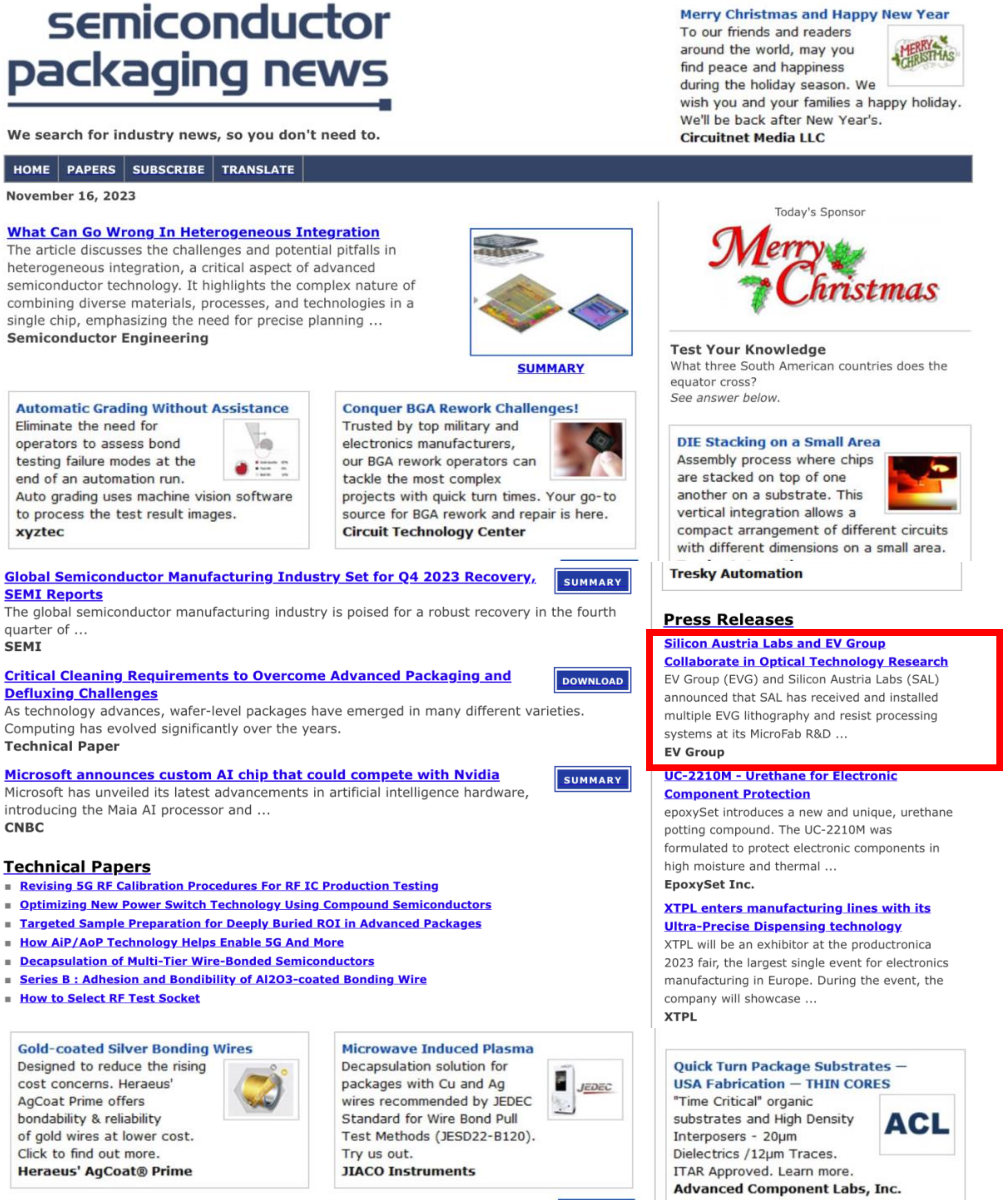
Silicon Austria Labs and EV Group Collaborate in Optical Technology Research – November 16, 2023



semiconductor packaging news

We search for industry news, so you don't need to.

Merry Christmas and Happy New Year
To our friends and readers around the world, may you find peace and happiness during the holiday season. We wish you and your families a happy holiday. We'll be back after New Year's.
Circuitnet Media LLC

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November 16, 2023

What Can Go Wrong In Heterogeneous Integration
The article discusses the challenges and potential pitfalls in heterogeneous integration, a critical aspect of advanced semiconductor technology. It highlights the complex nature of combining diverse materials, processes, and technologies in a single chip, emphasizing the need for precise planning ...
Semiconductor Engineering

SUMMARY

Automatic Grading Without Assistance
Eliminate the need for operators to assess bond testing failure modes at the end of an automation run. Auto grading uses machine vision software to process the test result images.
xyztec

Conquer BGA Rework Challenges!
Trusted by top military and electronics manufacturers, our BGA rework operators can tackle the most complex projects with quick turn times. Your go-to source for BGA rework and repair is here.
Circuit Technology Center

Global Semiconductor Manufacturing Industry Set for Q4 2023 Recovery, SEMI Reports
SUMMARY
The global semiconductor manufacturing industry is poised for a robust recovery in the fourth quarter of ...
SEMI

Critical Cleaning Requirements to Overcome Advanced Packaging and Defluxing Challenges
DOWNLOAD
As technology advances, wafer-level packages have emerged in many different varieties. Computing has evolved significantly over the years.
Technical Paper

Microsoft announces custom AI chip that could compete with Nvidia
SUMMARY
Microsoft has unveiled its latest advancements in artificial intelligence hardware, introducing the Maia AI processor and ...
CNBC

Technical Papers
- Revising 5G RF Calibration Procedures For RF IC Production Testing
- Optimizing New Power Switch Technology Using Compound Semiconductors
- Targeted Sample Preparation for Deeply Buried ROI in Advanced Packages
- How AiP/AoP Technology Helps Enable 5G And More
- Decapsulation of Multi-Tier Wire-Bonded Semiconductors
- Series B : Adhesion and Bondibility of Al2O3-coated Bonding Wire
- How to Select RF Test Socket

Gold-coated Silver Bonding Wires
Designed to reduce the rising cost concerns. Heraeus' AgCoat Prime offers bondability & reliability of gold wires at lower cost. Click to find out more.
Heraeus' AgCoat® Prime

Microwave Induced Plasma
Decapsulation solution for packages with Cu and Ag wires recommended by JEDEC Standard for Wire Bond Pull Test Methods (JESD22-B120). Try us out.
JIACO Instruments

Today's Sponsor
Merry Christmas

Test Your Knowledge
What three South American countries does the equator cross?
See answer below.

DIE Stacking on a Small Area
Assembly process where chips are stacked on top of one another on a substrate. This vertical integration allows a compact arrangement of different circuits with different dimensions on a small area.
Tresky Automation

Press Releases

Silicon Austria Labs and EV Group Collaborate in Optical Technology Research
EV Group (EVG) and Silicon Austria Labs (SAL) announced that SAL has received and installed multiple EVG lithography and resist processing systems at its MicroFab R&D ...
EV Group

UC-2210M - Urethane for Electronic Component Protection
epoxySet introduces a new and unique, urethane potting compound. The UC-2210M was formulated to protect electronic components in high moisture and thermal ...
EpoxySet Inc.

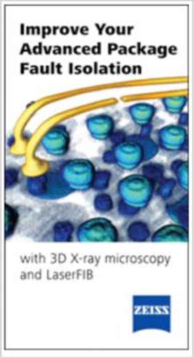
XTPL enters manufacturing lines with its Ultra-Precise Dispensing technology
XTPL will be an exhibitor at the productronica 2023 fair, the largest single event for electronics manufacturing in Europe. During the event, the company will showcase ...
XTPL

Quick Turn Package Substrates — USA Fabrication — THIN CORES
"Time Critical" organic substrates and High Density Interposers - 20µm Dielectrics /12µm Traces. ITAR Approved. Learn more.
Advanced Component Labs, Inc.

Sustainability 101: A Closer Look at E-waste
SUMMARY
This article examines the pressing issue of electronic waste (e-waste). It delves into the environmental and ...
3DInCites

Banned US chipmaking equipment still ending up in China
SUMMARY
China's chipmaking ambitions face a setback as the US imposes stricter export controls on critical semiconductor ...
The Register

Huawei's 5G chip breakthrough needs a reality check
SUMMARY
Huawei, the Chinese tech giant, has unveiled its latest 5G smartphone despite ongoing sanctions from the ...
MIT Technology Review



India's Wearable Market Grew 29.2% YoY to 48.1 Million Units, Says IDC
SUMMARY
India's wearable market is on a roll, as the International Data Corporation (IDC) reports a stellar ...
IDC

Imec unveils a publicly accessible 'virtual fab' in an effort to realize net zero in chip fabrication
SUMMARY
IMEC, a leading research and innovation hub in nanoelectronics and digital technologies, has announced ambitious plans ...
Digitimes

Chip inventory of Samsung, SK hynix remains high in Q3
SUMMARY
Samsung Electronics and SK hynix have reported high semiconductor inventories in the third quarter of this ...
The Korea Times

TSMC founder in US for APEC meet
SUMMARY
Morris Chang, the founder of Taiwan Semiconductor Manufacturing Co (TSMC), has arrived in San Francisco to ...
Taipei Times

Quote of the Day
"If I have seen farther than other men, it is because I stood on the shoulders of giants."
Sir Isaac Newton

The day was Nov 16. What year was it?
Pizarro Traps Incan Emperor

Francisco Pizarro, the Spanish explorer and conquistador, springs a trap on the Incan emperor, Atahualpa.
See the answer below.

Cartoon of the Day

"I found you a donor for an attitude transplant."

Fusion and Hybrid Bonding Experts

EVG's industry-leading process solutions, expertise and HI Competence Center accelerate the development and implementation of heterogeneous integration technology.

EV Group

Calendar

- Nov 16, 2023: Advanced Semiconductor Technology Conference (ASTC) 2023 November
- Dec 7, 2023: SiC—Silicon Carbide Webinar Series
- Dec 13, 2023: SEMICON Japan 2023
- Jan 7, 2024: ISS 2024—Industry Strategy Symposium

Essential Inspection Requirements in the Era of Convergence

Herein, learn ways to optimize processes and boost quality as advanced packages and board assembly converge. Read more.

Koh Young America, Inc.

Die Bonding Pattern Recognition

Learn the challenges of vision processing and pattern recognition for die bonding and a state-of-the-art technology that uses radar referencing, synthetic models, and active feedback.

Palomar Technologies, Inc.

Test Your Knowledge Answer

What three South American countries does the equator cross?

Answer: Brazil, Colombia, Ecuador

What Year Was It Answer

Pizarro Traps Incan Emperor

Answer: November 16, 1532

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